Form PTO-1595 (Rev. 09/ 04) OMB Na. 0651-0027 (exp. 8/30/2005)	U.S. DEPARTMENT OF COMMER United States Palont and Trademark Of
RECORDATION FOI	RM COVER SHEET
PATENTS ONLY	
To the Director of the U.S. Patent and Trademark Office: Please	e record the attached documents or the new address(es) below.
Name of conveying party(ies)/Execution Date(s):	2. Name and address of receiving party(les)
TSUYOSHI TAKAGI	
	Name: SONY CORPORATION
Form the Betalek November 199	Internal Address:
Execution Date(s): November 13, 2008 Additional name(s) of conveying party(ies) attached? Yes X No	Street Address:
	1-7-1 Konan, Minato-ku Tokyo
3. Nature of Conveyance: X Assignment Merger	108-0075
	JAPAN
Security Agreement Change of Name Government Interest Assignment	City:
Executive Order 9424, Confirmatory License	State:
Other	Country: Zip:
	Additional name(s) & address(es) Yes X No attached:
Additional numbers attached?	Yes X No
Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Dennis M. Smid, Esq. LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
nternal Address: Atty. Dkt.;	Authorized to be charged by credit card
Street Address: 600 South Avenue West	Authorized to be charged to deposit account Enclosed None required (government Interest not affecting title)
Dity: Westfield	8. Payment Information
tate: NJ Zip: 07090	a. Credit Card Last 4 Numbers
hone Number: (908) 518-6374	Expiration Date
fax Number: (908) 654-0415	b. Deposit Account Number 12-1095
mail Address: dsmid@ldlkm.com	Authorized User Name Dennis M. Smid, Esq.
Signature:	
Signature	November 20, 2008
Dennis M. Smid, Esq 34,930	Telef sumbas of second leaders as a second
Name of Person Signing	sheet, attachments, and documents; 2

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PATENT REEL: 021873 FRAME: 0159

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LERNER, LITTENBE ;0367483553

Docket No.: SONYJP 3.0-1582 Sony Ref. No.: S08P0343US00

☑ 003/003

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

INFORMATION PROCESSING APPARATUS, METHOD, AND PROGRAM

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accoming or to account to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 12/074,230; Filing Date: February 29, 2008.

This assignment executed on the dates indicated below.

Tsuvoshi TAKAGI	
Name of First or Sole Inventor	Execution Date of U.S. Patent Application
Kanagawa, Japan	
Residence of First or Sole Inventor	M
Signature of First or Sole Inventor	Notember 13, 200 P Date of this Assignment

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RECORDED: 11/20/2008